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Docket No. 0756243401 B

6/26/03

C. Moore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of) Art Unit: 2818
Shunpei YAMAZAKI et al.) Examiner: D. Le
Serial No. 10/074,050)
Filed: February 14, 2002)
For: METHOD OF MANUFACTURING) A SEMICONDUCTOR DEVICE)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 16, 2003.

Adrian M. Stampu

AMENDMENT & RESPONSE TO ELECTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of April 16, 2003, please amend the subject application as follows:

IN THE CLAIMS:

Cancel claims 180-211 without prejudice to applicant's right to file a divisional application with respect thereto.

Please add new claims 212-262 as follows:

--212. A method of manufacturing a semiconductor device comprising the steps of:

adding a metal element to a first semiconductor film comprising amorphous silicon over a substrate;

crystallizing the first semiconductor film to form a first crystalline semiconductor film;

forming a second semiconductor film over the first crystalline semiconductor film;

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03 FC:1202

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